

Insignis California Proposition 65 Statement

According to California Proposition 65 published by The Office of Environmental Health Hazard Assessment on Aug. 2016, Insignis Technology Corporation (“Insignis”) has used its commercially reasonable efforts to survey its suppliers and has acquired the relevant information therefrom. This statement is valid for all Insignis products, including all Insignis DRAM and Flash Memories. Pursuant to such acquired relevant information, Insignis hereby provides its statement regarding the “Insignis product’s Substances Content Table” as set forth hereunder:

Substances Content Table

Item	Substance	CAS#	Application Area	Concentration from the material listed in Application Area (ppm)
1	Acrylonitrile	107-13-1	Lead frame tape	<0.6
2	Aniline	62-53-3	Molding compound	<1
3	Antimony oxide (Antimony trioxide)	1309-64-4	Lead frame tape	< 400
4	Benz[a]anthracene	56-55-3	Molding compound	< 800
5	Benzene	71-43-2	Lead frame tape	< 5
6	Benzo[b]fluoranthene	205-99-2	Molding compound	< 800
7	Benzo[j]fluoranthene	205-82-3	Molding compound	< 800
8	Benzo[k]fluoranthene	207-08-9	Molding compound	< 800
9	Benzo[a]pyrene	50-32-8	Molding compound	< 800
10	Beryllium and beryllium compounds	-	Gold wire	<13
11	Cadmium and cadmium compounds	-	Plating	< 20

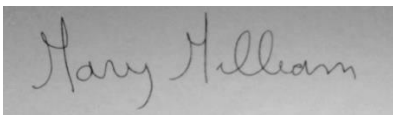
Item	Substance	CAS#	Application Area	Concentration from the material listed in Application Area (ppm)
12	Carbon black (airborne, unbound particles of respirable size)	1333-86-4	Molding compound	<10000
13	Chrysene	218-01-9	Molding compound	< 800
14	Dibenz[a,h]acridine	226-36-8	Molding compound	< 800
15	Dibenz[a,j]acridine	224-42-0	Molding compound	< 800
16	Dibenz[a,c]anthracene	215-58-7	Molding compound	< 800
17	Dibenz[a,h]anthracene	53-70-3	Molding compound	< 800
18	Dibenz[a,j]anthracene	224-41-9	Molding compound	< 800
19	7H-Dibenzo[c,g]carbazole	194-59-2	Molding compound	< 800
20	Dibenzo[a,e]pyrene	192-65-4	Molding compound	< 800
21	Dibenzo[a,h]pyrene	189-64-0	Molding compound	< 800
22	Dibenzo[a,i]pyrene	189-55-9	Molding compound	< 800
23	Dibenzo[a,l]pyrene	191-30-0	Molding compound	< 800
24	Diethanolamine	111-42-2	Gold wire	<3600
25	Ethylbenzene	100-41-4	Lead frame tape	< 0.5
26	Formaldehyde (gas)	50-00-0	Lead frame tape	< 50
27	Indeno [1,2,3-cd]pyrene	193-39-5	Molding compound	< 800
28	Lead and lead compounds	-	Plating	< 500
29	Methanol	67-56-1	Leadframe	<0.06
30	N-Methylpyrrolidone	872-50-4	Leadframe	<510

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Item	Substance	CAS#	Application Area	Concentration from the material listed in Application Area (ppm)
31	1-Nitropyrene	5522-43-0	Molding compound	< 800
32	4-Nitropyrene	57835-92-4	Molding compound	< 800
33	Silica, crystalline (airborne particles of respirable size)	-	Molding compound	< 50000
34	Toluene	108-88-3	Tape	<900
35	Nickel	7440-02-0	lead frame	<32000

This signature below verifies that the statement above is valid and accurate.

Insignis Technology Corporation
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Date: 10/22/24